



Material Content Data Sheet



Sales Product Name				IPG20N06S2L-50		Issued		4. October 2018	
MA#				MA000685674					
Package				PG-TDSON-8-4		Weight*		96.85 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	1.164	1.20	1.20	12018	12018	
chip_2	inorganic material	silicon	7440-21-3	1.164	1.20	1.20	12018	12018	
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		138		
	non noble metal	iron	7439-89-6	0.044	0.05		459		
wire	non noble metal	copper	7440-50-8	44.409	45.86	45.92	458549	459146	
	non noble metal	aluminium	7429-90-5	0.760	0.78	0.78	7850	7850	
encapsulation	organic material	carbon black	1333-86-4	0.090	0.09		928		
	plastics	epoxy resin	-	6.383	6.59		65904		
leadfinish	inorganic material	silicondioxide	60676-86-0	38.475	39.73	46.41	397279	464111	
	non noble metal	tin	7440-31-5	1.308	1.35	1.35	13502	13502	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.048	0.05	0.05	495	496	
solder	non noble metal	tin	7440-31-5	0.055	0.06		567		
	noble metal	silver	7440-22-4	0.069	0.07		708		
heatspreader	non noble metal	lead	7439-92-1	2.620	2.71	2.84	27051	28326	
	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
*deviation	non noble metal	iron	7439-89-6	0.000	0.00		3		
	non noble metal	copper	7440-50-8	0.245	0.25	0.25	2529	2533	
Sum in total:						100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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